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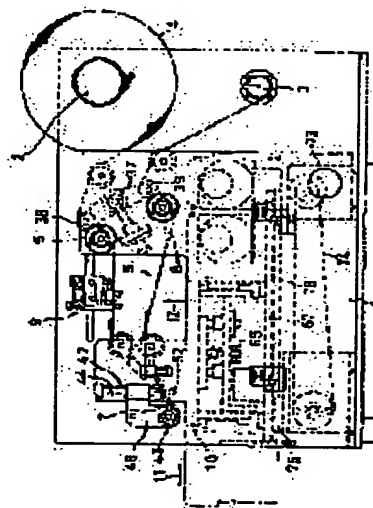
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(54) ADHESIVE TAPE STICKING DEVICE

(57)Abstract:

PURPOSE: To obtain an inexpensive adhesive tape sticking device which has such a simple constitution that a semiconductor wafer can be manually set to a ring frame and no special apparatus is required for giving tension to an adhesive tape.

CONSTITUTION: A peel plate 7 which peels an adhesive tape from a release frame 5 and a press roller 43 which is provided near the plate 7 and makes free rotation when the roller 43 is moved at its upper position and driven rotation when the roller 43 is moved at its lower position are provided and a table 56 mounted with a semiconductor wafer and ring frame is provided in such a state that the table 56 can freely make reciprocating motions between a position below the roller 43 and another position separated from the position and the table 56 can be brought into contact and separated from the roller 43. The release film 5 is driven by means of a torque motor and a tension roller 6 which works in conjunction with a pinch roller and a drive roller 8 give tension to the film.



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